

Transfer field

TF-P-SI-030-L

Item 48740



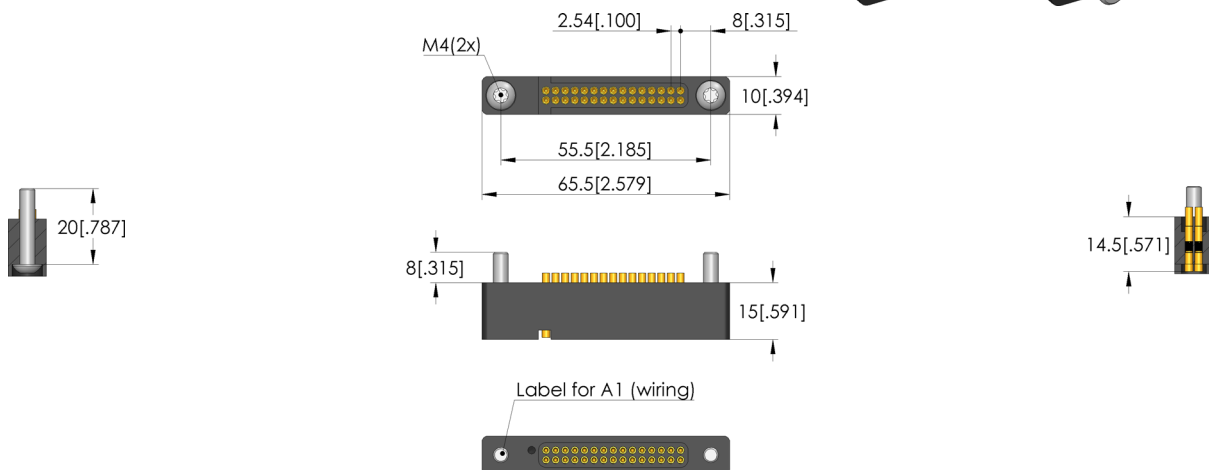
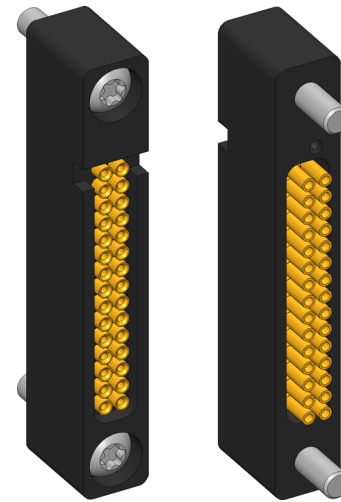
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- Contact module for reliable transmission of signals when contacting from the top side
- Quick, easy, freely adjustable installation
- Equipped with INGUN contact terminals

Application

Transfer fields (TF) are used as contact modules to reliably transmit signals from top-side contacting. The signal transfer is spring-loaded, with the advantage that the exchangeable kit can be exchanged quickly and easily in interchangeable kit test fixtures without having to disconnect the wiring to the DUT. Transfer fields are typically mounted on the pressure-frame plate.



General data

Product group:
Series:
Type:
Version:
Accessory type:
Scope of delivery:
Width:
Height:
Weight:
Min. temperature:
Max. temperature:
RoHS-compliant:

Transfer fields
TF-SI

Device under test (DUT) side
Customising accessories
Fully loaded with KT-254 L3 E02
10 mm [.393 in]
15 mm [.59 in]
0.02 kg [.044 lbs]
10 °C [50 °F]
60 °C [140 °F]
Yes

Compatible with

Exchangeable kits version:
MA exchangeable kits (ATS MA):
For dual-stage contacting:

No limitations
ATS MAxx
Yes

Technical data

Connection:
Number of poles: 30
Installation grid: 2.54 mm [.1 in]
Length: 65.5 mm [2.57 in]
Outer dimensionS (WxDxH): 65.5 x 10 x 15 mm [2.57 x .393 x .59 in]

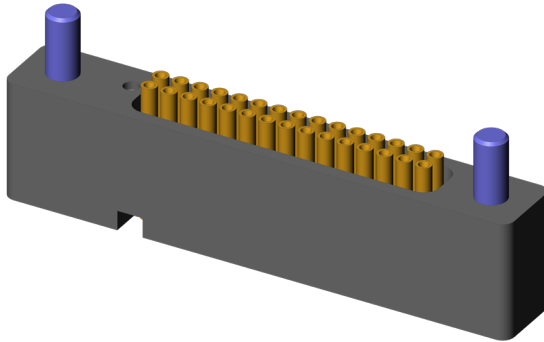
Solder connection

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